

IN THE SPECIFICATION

Please replace the paragraph at page 3, lines 5-12, with the following rewritten paragraph:

A variety of studies have been made to cope with reduction of solder bump pitches. For example, ~~JP-A-H10-350230~~ JP-A-H06-350230 discloses formation of a peelable solder dam resist on a solder resist, and JP-A-2000-208911 discloses a method wherein a dry film is laminated on the solder resist layer, apertures are created at positions corresponding to electrode pads, a solder paste is applied followed by reflowing, and the dry film is peeled.